Materials Declaration Form

IPC	1752	Version	2
Form Type *	Distribute		
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D * : Required Field

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2013-10-16
Contact Name *	Refer to " Supplier Comment" section	Contact Title	Refer to " Supplier Comment" section
Contact Phone *	Refer to " Supplier Comment" section	Contact Email *	Refer to " Supplier Comment" section
Authorized Representative *	Laurent Tosi	Representative Title	MMS MD CHAMPION
Representative Phone *	(+33) 442 685 795	Representative Email *	laurent.tosi@st.com
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/online_tech_support.html		

Uncertainty Statement

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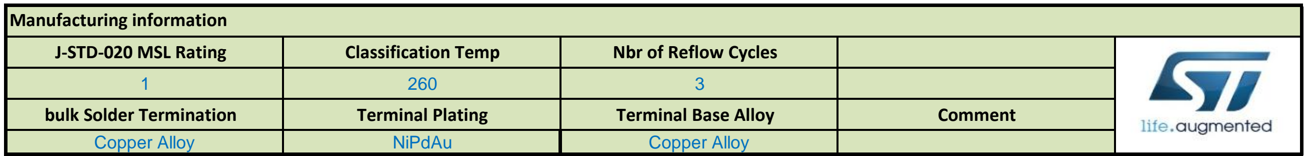
Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard

Legal Statement	Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as omprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	**Mfr Item Name**	**Version**	**Mfr Site**	**Date**
-	PGO7*2SF31UA	A	Shenzhen	2013-10-15
	Amount	**UoM**	**Unit type**	**ST ECOPACK Grade**
	80.00	mg	Each	ECOPACK® 2



Manufacturing information				
J-STD-020 MSL Rating	**Classification Temp**	**Nbr of Reflow Cycles**		
1	260	3		
bulk Solder Termination	**Terminal Plating**	**Terminal Base Alloy**	**Comment**	
Copper Alloy	NiPdAu	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
SON	3.9 x 4.9 x 1.250	8	L bend	
Comment	SO8N			

QueryList : ROHS directive 2011/65/EU _ July 2011		
Query		**Response**
Product(s) meets EU RoHS requirement without any exemptions		**true**
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)		false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)		false
Product(s) does not meet EU RoHS requirements and is not under exemptions		false
Product(s) is obsolete, no information is available		false
Product(s) is unknown, no information is available		false
Exemption Id.	**Description**	

QueryList :REACH-20th June 2013				
Query				**Response**
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				**true**
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	PGO7*2SF31UA					
Homogeneous Material	**Material Group**	**Mass**	**UoM**	**Level**	**Substance Category**	**Substance**	**CAS**	**Exempt**	**Mass**	**UoM**	**Concentration in homogeneous material (ppm)**	**Concentration in product (ppm)**
die (s)	Other inorganic materials	1.90	mg	supplier	die	Silicon (Si)	7440-21-3		1.82	mg	958399.00	22750.00
die (s)				supplier	metallization	Aluminium (Al)	7429-90-5		0.01	mg	3686.00	88.00
die (s)				supplier	metallization	Copper (Cu)	7440-50-8		0.01	mg	3686.00	88.00
die (s)				supplier	metallization	Titanium (Ti)	7440-32-6		0.00	mg	527.00	13.00
die (s)				supplier	metallization	Tungsten (W)	7440-33-7		0.00	mg	527.00	13.00
die (s)				supplier	passivation	Silicon Nitride (SiN)	68034-42-4		0.01	mg	2633.00	63.00
die (s)				supplier	passivation	Silicon Oxide(SiO2)	7631-86-9		0.06	mg	30542.00	725.00
Lead-frame	Other inorganic materials	24.98	mg	supplier	alloy	Copper (Cu)	7440-50-8		24.35	mg	974500.00	304333.00
Lead-frame				supplier	alloy	Iron (Fe)	7439-89-6		0.59	mg	23460.00	7326.00
Lead-frame				supplier	alloy	Zinc (Zn)	7440-66-6		0.03	mg	1200.00	375.00
Lead-frame				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.02	mg	840.00	262.00
Lead-frame Coating	Other inorganic materials	0.12	mg	supplier	coating	Nickel (Ni)	7440-02-0		0.11	mg	916800.00	1425.00
Lead-frame Coating				supplier	coating	Palladium (Pd)	7440-05-3		0.01	mg	58700.00	91.00
Lead-frame Coating				supplier	coating	Gold (Au)	7440-57-5		0.00	mg	24500.00	38.00
Die Attach	Other inorganic materials	1.28	mg	supplier	glue or soft solder	Silver (Ag)	7440-22-4		1.15	mg	900000.00	14369.00
Die Attach				supplier	glue or soft solder	acrylate	na		0.08	mg	60000.00	958.00
Die Attach				supplier	glue or soft solder	Methacrylate	na		0.05	mg	38000.00	607.00
Die Attach				supplier	glue or soft solder	acrylate	na		0.00	mg	2000.00	32.00
Wires	Other inorganic materials	0.06	mg	supplier	Bonding wire	Gold (Au)	7440-57-5		0.06	mg	1000000.00	776.00
Encapsulation	Other inorganic materials	51.65	mg	supplier	Moulding Compound	Epoxy Resin	na		3.88	mg	75115.00	48498.00
Encapsulation				supplier	Moulding Compound	Phenol Resin	na		2.59	mg	50076.00	32332.00
Encapsulation				supplier	Moulding Compound	Silica, vitreous	60676-86-0		44.72	mg	865795.00	559000.00
Encapsulation				supplier	Moulding Compound	Carbon-black	1333-86-4		0.26	mg	5008.00	3233.00
Encapsulation				supplier	Moulding Compound	Bismuth (Bi)	7440-69-9		0.21	mg	4006.00	2587.00
Finishing	Other inorganic materials	0.00	mg	supplier	connections coating	Nickel (Ni)	7440-02-0		0.00	mg	916800.00	14.00
Finishing				supplier	connections coating	Palladium (Pd)	7440-05-3		0.00	mg	58700.00	1.00